

# GPU A+ Server AS -8125GS-TNHR



More details here

## Key Applications

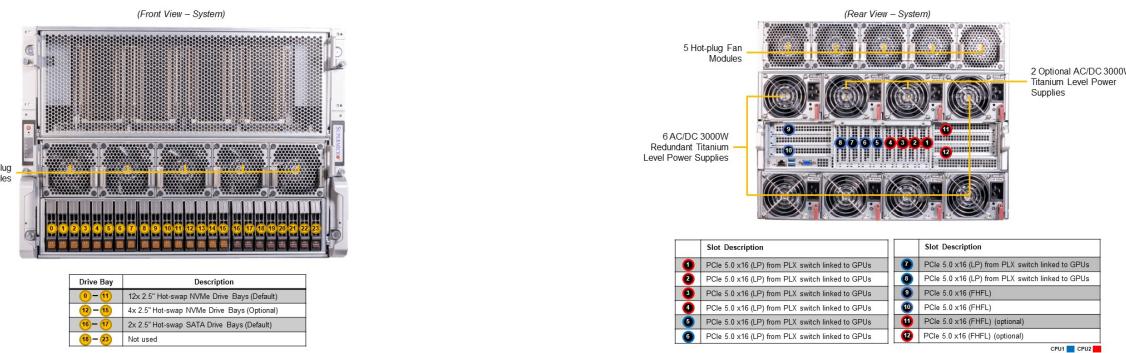
High Performance Computing, AI/Deep Learning Training, Industrial Automation, Retail, Climate and Weather Modeling,

## Key Features

- Highest GPU communication using NVIDIA® NVLINK™ + NVIDIA® NVSwitch™; 8 NIC for GPU direct RDMA (1:1 GPU Ratio); High density 8U system with NVIDIA® HGX™ H100 8-GPU;
- 24 DIMM Slots; Up to 6TB DRAM; 4800 ECC DDR5 RDIMM; RDIMM;;
- 8 PCIe Gen 5.0 X16 LP, and up to 4 PCIe Gen 5.0 X16 FHFL Slots;
- Flexible networking options;
- 1 M.2 NVMe for boot drive only; up to 16x 2.5" Hot-swap NVMe drive bays (12 by default + 4 optional); 2x 2.5" Hot-swap SATA drive bays;
- 10 heavy duty fans with optimal fan speed control;
- 6x 3000W redundant Titanium level power supplies;



Form Factor	8U Rackmount Enclosure: 437 x 355.6 x 843.28mm (17.2" x 14" x 33.2") Package: 698 x 750 x 1300mm (27.5" x 29.5" x 51.2")
Processor	Dual Socket SP5 AMD EPYC™ 9004 Series Processors (the latest AMD EPYC™ 9004 Series Processor with AMD 3D V-Cache™ Technology) Up to 128C/256T Supports up to 400W TDP CPUs (Air Cooled)
GPU	Supported GPU: HGX H100 8-GPU SXM5 Multi-GPU Board CPU-GPU Interconnect: PCIe 5.0 x16 CPU-to-GPU Interconnect GPU-GPU Interconnect: NVIDIA® NVLink™ with NVSwitch™
System Memory	Memory Capacity: 24 DIMM slots Up to 6TB: 24x 256 GB DRAM Memory Type: 4800MHz ECC DDR5 RDIMM/LRDIMM
Drive Bays	18x 2.5" hot-swap NVMe/SATA drive bays (16x 2.5" NVMe dedicated) 1 M.2 NVMe
Expansion Slots	8 PCIe 5.0 x16 LP slot(s) 2 PCIe 5.0 x16 FHFL slot(s)
On-Board Devices	Chipset: AMD SP5 Network Connectivity:
Input / Output	Video: 1 VGA port(s)



System Cooling	10 heavy duty fan(s)
Power Supply	6x 3000W Redundant Titanium Level power supplies
System BIOS	BIOS Type: AMI 32MB SPI Flash EEPROM
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory 7 +1 Phase-switching voltage regulator FAN: Fans with tachometer monitoring Status monitor for speed control Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors
Dimensions and Weight	Height: 14" (355.6 mm) Width: 17.2" (437 mm) Depth: 33.2" (843.28 mm) Gross Weight: 225 lbs (102.1 kg) Net Weight: 166 lbs (75.3 kg) Packaging: 29.5" (H) x 27.5" (W) x 51.2" (D) Available Color: Black Front & Silver Body
Operating Environment	Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	<a href="#">Super H13DSG-O-CPU-D</a>
Chassis	CSE-GP801TS